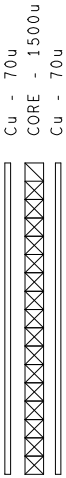


FABRICATION NOTE:

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVSTDRV611MC R2 FOR CIRCUIT PATTERN.
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STMICROelectronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C (High Tg)
- 5:SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABRICATION.STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS, APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DETAIL 'A'
LAYER BUILD UP
(reference only)



(external Cu th are after plating)
estimated total thickness 1640u

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	9.84	PLATED	693
B	27.56	PLATED	2
C	27.95	PLATED	14
D	31.5	PLATED	1
E	35.43	PLATED	9
F	43.31	PLATED	10
G	44.02	PLATED	10
H	47.24	PLATED	4
I	51.18	PLATED	4
L	62.6	PLATED	4
M	62.99	PLATED	8
N	78.74	PLATED	2
O	125.98	NON-PLATED	4

TOTAL HOLES: 765

Finished Hole Tolerance - All units are in Inches -			
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter	
0.008"-0.013"	+0.002/-FHS"	+/-0.002"	
0.014"-0.063"	+/-0.003"	+/-0.002"	
0.064"-0.156"	+/-0.004"	+/-0.003"	
0.157"-0.250"	+/-0.007"	+/-0.004"	
0.251" and up	+/-0.007"	+/-0.005"	
0.125"	Non Plated Only	+0.003/-0.000"	

REVISION DATE: 26-May-25



APMS Group AGRATE B. ITALY

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Drawn RIGO M. date 20-Mar-2025
Approved date

Description

DRILLING AND PROFILING

Symbol

EVSTDRV611MC
Group

SCALE: 1 : 1
REV. 2.0



Material

Treatment and surface finishing